Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-11. (Canceled).

- 12. (New) Microstructure comprising an adhesive layer between a substrate and a photo-patternable layer, the adhesive layer being photosensitive, arranged on at least one face of the substrate and being formed by a negative resin comprising at least one polymer of the elastomer family and at least one photo-initiating component, in solution in an aromatic solvent.
- 13. (New) Microstructure according to claim 12, wherein the polymer is a cyclic polyisoprene in solution in xylene.
- 14. (New) Microstructure according to claim 12, wherein the adhesive layer has a thickness comprised between 200nm and 10μm.
- 15. (New) Microstructure according to claim 12, wherein the photo-patternable layer is formed by at least one negative resin of epoxy type.
- 16. (New) Microstructure according to claim 12, wherein the photo-patternable layer has a thickness comprised between 50μm and 200μm.

- 17. (New) Microstructure according to claim 12, wherein the substrate is formed by a material selected from the group consisting of silicon, glass and plastics.
- 18. (New) Method of fabrication of a microstructure according to claim 12, comprising spreading and drying of an adhesive layer formed by a negative resin comprising at least one polymer of the elastomer family and at least one photo-initiating component, in solution in an aromatic solvent, before deposition of at least one photo-patternable layer of resin.
- 19. (New) Fabrication method according to claim 18, wherein the adhesive layer is exposed through a mask and developed, before deposition of the photo-patternable layer.
- 20. (New) Fabrication method according to claim 18, wherein the adhesive layer and the photo-patternable layer are exposed simultaneously through a mask.
- 21. (New) Fabrication method according to claim 20, wherein the photo-patternable layer and the adhesive layer are developed successively.
- 22. (New) Fabrication method according to claim 18, wherein at least two photopatternable layers are developed simultaneously, after having been successively deposited and exposed through two different masks.